and Fig. 33F are graphs showing various relations between the amount of the inorganic filler of the anisotropic conductive layer employed by the method and apparatus for mounting the electronic component of, for example, an IC chip on the circuit board of the fourteenth embodiment and the position in the direction of thickness of the anisotropic conductive layer;

Fig. 34 is an explanatory view of a manufacturing process of the anisotropic conductive layer employed by a method and apparatus for mounting an electronic component of, for example, an IC chip on a circuit board according to a fifteenth embodiment of the present invention;

Fig. 35 is a partially enlarged view of Fig. 34;

Fig. 36 is a graph of the distribution of the mean diameter of the conductive particles and the mean diameter of the particles of an inorganic filler in one concrete example of the first embodiment;

Fig. 37A and Fig. 37B are views showing examples of the bumps that can be employed according to modification examples of the first embodiment;

Fig. 38A, Fig. 38B, Fig. 38C, Fig. 38D, Fig. 38E, Fig. 38F and Fig. 38G are explanatory views showing a method and apparatus for mounting an electronic component of, for example, an IC chip on a circuit board according to a sixteenth embodiment of the present invention;

Fig. 39A and Fig. 39B are explanatory views showing a state in which an inorganic filler in a thermosetting resin is forced outwardly of a bump due to a pointed bump that enters the thermosetting resin at the beginning of bonding by a method for mounting an electronic component of, for example, an IC chip on a circuit board according to a sixteenth embodiment, and Fig. 39C is an explanatory view of a state in which no inorganic filler enters a space between the bump and the board electrode;

Fig. 40A, Fig. 40B, Fig. 40C, Fig. 40D, Fig. 40E, Fig. 40F and Fig. 40G are explanatory views showing a bump forming process by means of a wire bonder for an IC chip by the mounting method of the sixteenth embodiment of the present invention;

Fig. 41A, Fig. 41B and Fig. 41C are explanatory views showing a process for bonding an IC chip to a circuit board by the mounting method of the sixteenth embodiment of the present invention;

Fig. 42A, Fig. 42B and Fig. 42C are explanatory views showing a process for bonding an IC chip to a circuit board by the mounting method of the sixteenth embodiment of the present invention;

Fig. 43A, Fig. 43B and Fig. 43C are explanatory views for explaining a thermosetting adhesive arranged on a circuit board in place of a thermosetting resin sheet by a

mounting method according to an eighteenth embodiment of the present invention;

Fig. 44A, Fig. 44B, Fig. 44C, Fig. 44D, Fig. 44E and Fig. 44F are explanatory views for explaining a thermosetting adhesive arranged on a circuit board according to modification examples of Fig. 43A through Fig. 43C in place of a thermosetting resin sheet by the mounting method of the eighteenth embodiment of the present invention;

Fig. 45A, Fig. 45B and Fig. 45C are explanatory views showing a process for bonding an IC chip to a circuit board by a mounting method according to a twentieth embodiment of the present invention;

Fig. 46A, Fig. 46B and Fig. 46C are explanatory views showing a process for bonding an IC chip to a circuit board by the mounting method of the twentieth embodiment of the present invention;

Fig. 47A, Fig. 47B, Fig. 47C and Fig. 47D are explanatory views showing a process for bonding an IC chip to a circuit board by a mounting method according to a twenty-first embodiment of the present invention;

Fig. 48A, Fig. 48B, Fig. 48C, Fig. 48D and Fig. 48E are explanatory views showing a process for bonding an IC chip to a circuit board by the mounting method of the twenty-first embodiment of the present invention;